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STPS30M120SR

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STPS30M120S

Power Schottky rectifier

Datasheet – production data

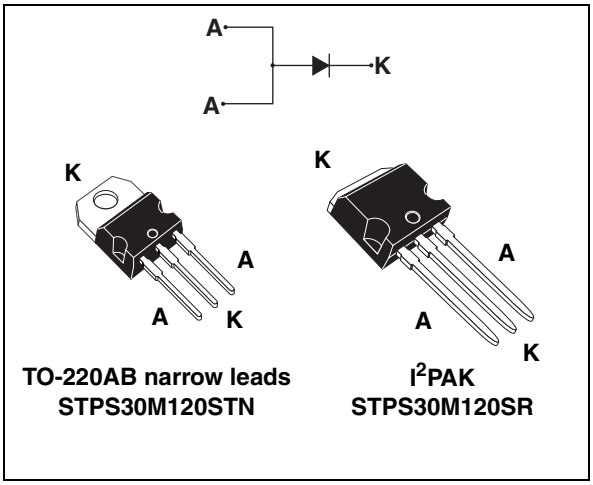
Features

- High current capability
- Avalanche rated
- Low forward voltage drop
- High frequency operation

Description

This Schottky diode is suited for high frequency switch mode power supply.

Packaged in TO-220AB narrow leads and I^2PAK, this device is intended to be used in notebook, game station and desktop adapters, providing in these applications a good efficiency at both low and high load.



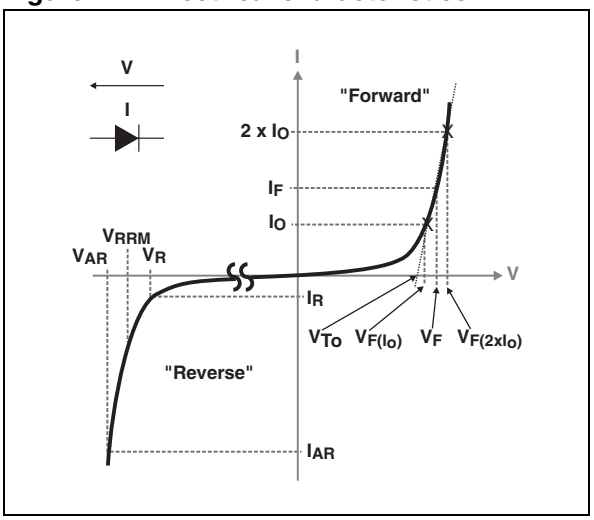
TO-220AB narrow leads
STPS30M120STN

I^2PAK
STPS30M120SR

Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	30 A
V_{RRM}	120 V
V_F (typ)	0.45 V
T_j (max)	150 °C

Figure 1. Electrical characteristics(a)



a. V_{ARM} and I_{ARM} must respect the reverse safe operating area defined in *Figure 9*. V_{AR} and I_{AR} are pulse measurements (t_p < 10 µs). V_R, I_R, V_{RRM} and V_F, are static characteristics

1 Characteristics

Table 2. Absolute ratings (limiting values with terminals 1 and 3 short circuited at T_{amb} = 25 °C, unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		120	V
$I_{F(RMS)}$	Forward rms current		50	A
$I_{F(AV)}$	Average forward current, δ = 0.5	T_c = 110 °C	30	A
I_{FSM}	Surge non repetitive forward current	t_p = 10 ms sine-wave	260	A
P_{ARM}(1)	Repetitive peak avalanche power	T_j = 125 °C, t_p = 10 µs	1450	W
V_{ARM}(2)	Maximum repetitive peak avalanche voltage	t_p < 10 µs, T_j < 125 °C, I_{AR} < 9.7 A	150	V
V_{ASM}(2)	Maximum single-pulse peak avalanche voltage	t_p < 10 µs, T_j < 125 °C, I_{AR} < 9.7 A	150	V
T_{stg}	Storage temperature range		-65 to +175	°C
T_j	Maximum operating junction temperature(3)		150	°C

1. For pulse time duration deratings, please refer to *Figure 4*. More details regarding the avalanche energy measurements and diode validation in the avalanche are provided in the STMicroelectronics Application notes AN1768, “Admissible avalanche power of schottky diodes” and AN2025, “Converter improvement using Schottky rectifier avalanche specification”.
2. See *Figure 9*
3. $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	1.3	°C/W

Table 4. Static electrical characteristics (terminals 1 and 3 short circuited)

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I_R(1)	Reverse leakage current	T_j = 25 °C	$V_R = V_{RM}$	-	70	345	µA
		T_j = 125 °C		-	25	65	mA
V_F(2)	Forward voltage drop	T_j = 125 °C	I_F = 5 A	-	0.45	0.50	V
		T_j = 125 °C	I_F = 10 A	-	0.52	0.57	
		T_j = 25 °C	I_F = 15 A	-		0.75	
		T_j = 125 °C		-	0.57	0.62	
		T_j = 25 °C	I_F = 30 A	-		0.90	
		T_j = 125 °C		-	0.66	0.73	

1. Pulse test: t_p = 5 ms, δ < 2%
2. Pulse test: t_p = 380 µs, δ < 2%

To evaluate the conduction losses use the following equation:
$P = 0.53 \times I_{F(AV)} + 0.0067 \times I_{F}{}^{2}{}_{(RMS)}$

Figure 2. Average forward power dissipation versus average forward current

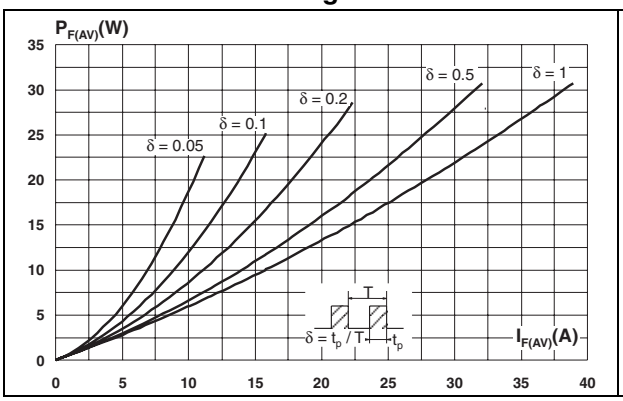


Figure 3. Average forward current versus ambient temperature (δ = 0.5)

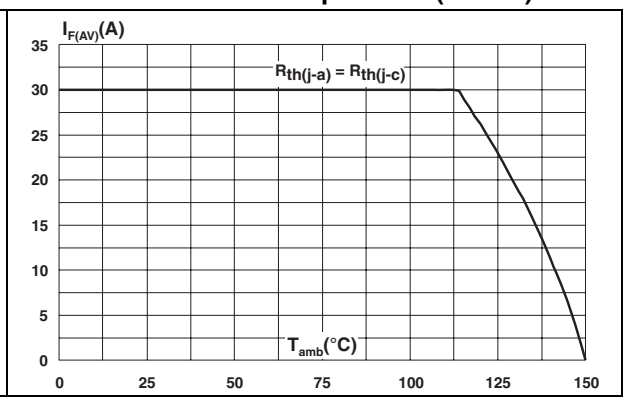


Figure 4. Normalized avalanche power derating versus pulse duration

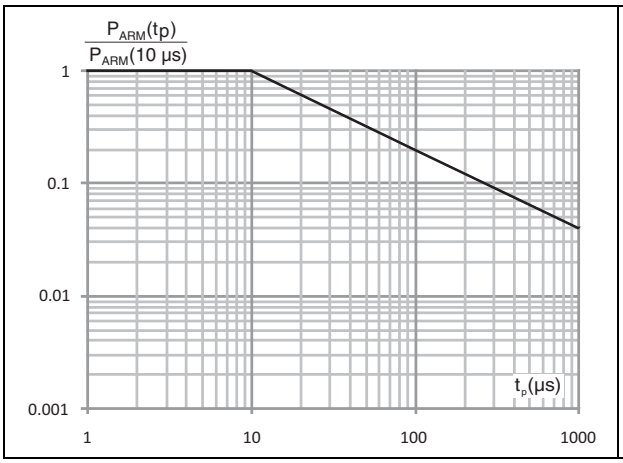


Figure 5. Relative variation of thermal impedance junction to case versus pulse duration

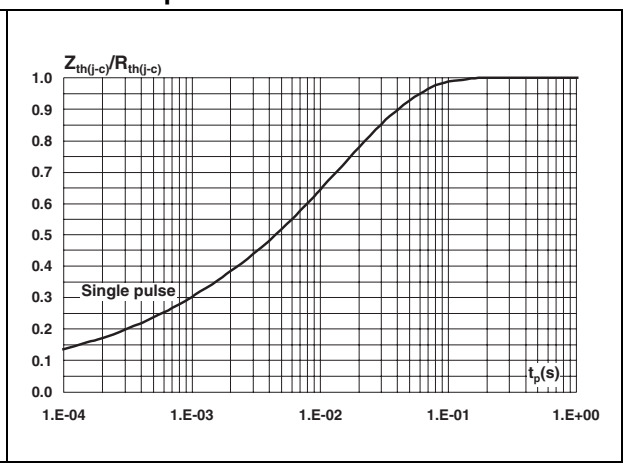


Figure 6. Reverse leakage current versus reverse voltage applied (typical values)

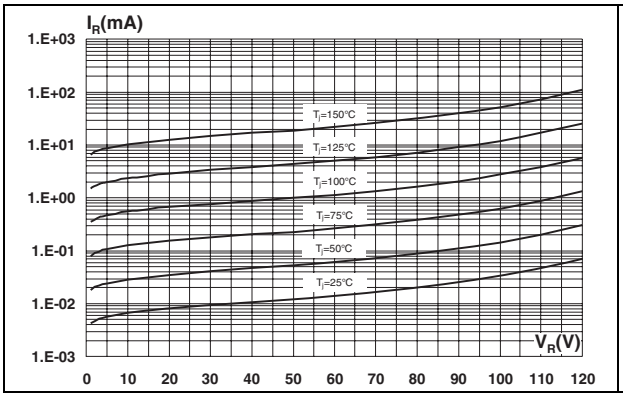


Figure 7. Junction capacitance versus reverse voltage applied (typical values)

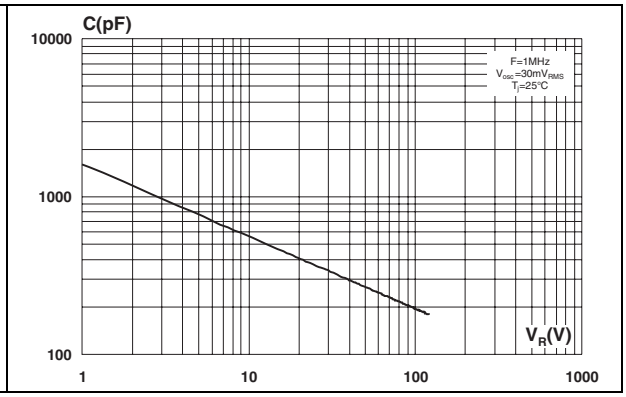


Figure 8. Forward voltage drop versus forward current

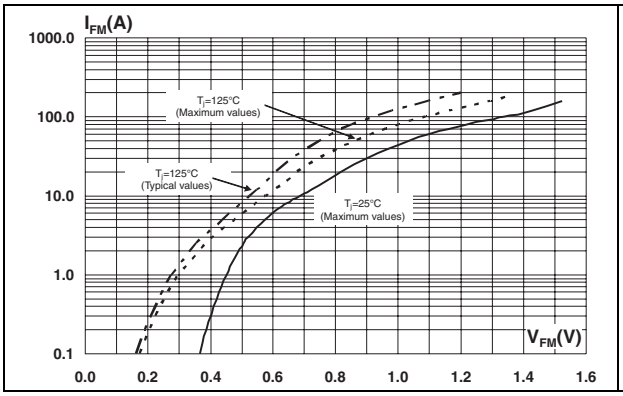
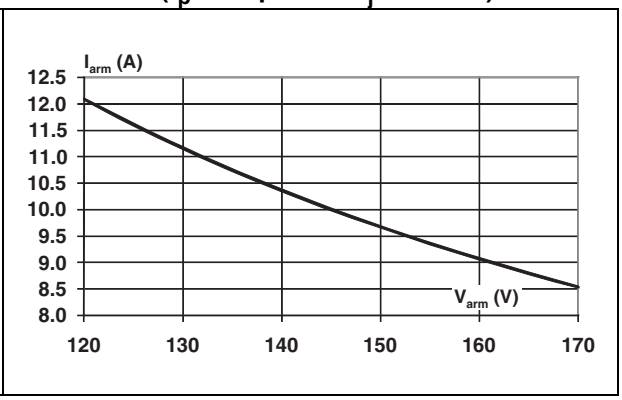


Figure 9. Reverse safe operating area (t_p < 10 µs and T_j < 125 °C)

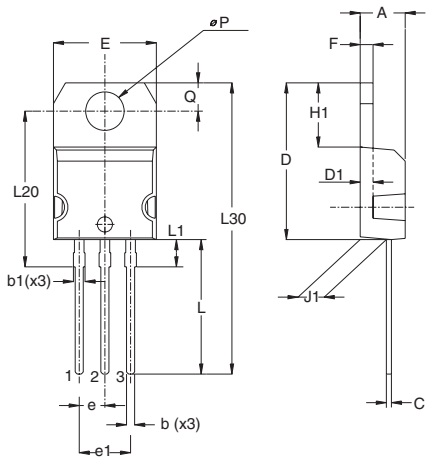


2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.4 to 0.6 N·m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

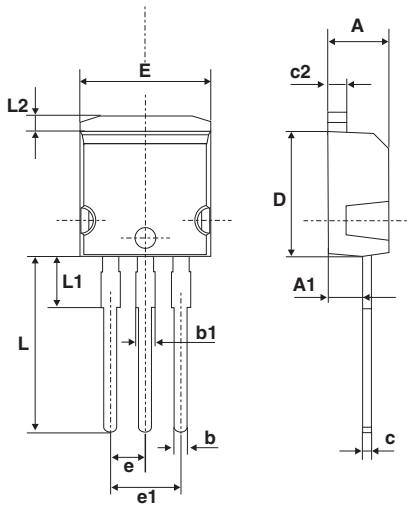
Table 5. TO-220AB narrow leads dimensions



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.17		0.18
b	0.61		0.88	0.024		0.034
b1	0.95		1.20	0.037		0.047
c	0.48		0.70	0.019		0.027
D	15.25		15.75	0.60		0.62
D1	1.27			0.05		
E	10.00		10.40	0.39		0.41
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.19		0.20
F	1.23		1.32	0.048		0.052
H1	6.20		6.60	0.24		0.26
J1	2.40		2.72	0.095		0.107
L	13.00		14.00	0.51		0.55
L1	2.60		2.90	0.102		0.114
L20	15.40			0.61		
L30	28.90			1.14		
∅P	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116

Devices in I^2PAK with nickel-plated back frame must NOT be mounted by frame soldering like SMDs. Such devices are intended to be through-hole mounted ONLY and in no circumstances shall ST be held liable for any lack of performance or damage arising out of soldering of nickel-plated back frames.

Table 6. I^2PAK dimensions



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.40	2.72	0.094	0.107
b	0.61	0.88	0.024	0.035
b1	1.14	1.70	0.044	0.067
c	0.49	0.70	0.019	0.028
c2	1.23	1.32	0.048	0.052
D	8.95	9.35	0.352	0.368
e	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
E	10	10.40	0.394	0.409
L	13	14	0.512	0.551
L1	3.50	3.93	0.138	0.155
L2	1.27	1.40	0.050	0.055

3 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS30M120SR	PS30M120SR	I^2PAK	1.49 g	50	Tube
STPS30M120STN	PS30M120STN	TO-220AB narrow leads	1.9 g	50	Tube

4 Revision history

Table 8. Document revision history

Date	Revision	Changes
02-Apr-2012	1	First issue.

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